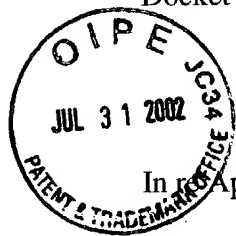


Docket No.: 5198/Consilium/MBE

PATENT/OFFICIAL AUG 01 2002  
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



In Application of

Parris C.M. HAWKINS et al.

Serial No. 09/800,980

Filed: March 8, 2001

For: DYNAMIC AND EXTENSIBLE TASK GUIDE

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Group Art Unit: 2121  
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**SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT**

Honorable Commissioner for Patents  
Washington, D. C. 20231

Sir:

In accordance with the provisions of 37 C.F.R. 1.56, 1.97 and 1.98, the attention of the Patent and Trademark Office is hereby directed to the documents listed on the attached form PTO-1449. It is respectfully requested that the documents be expressly considered during the prosecution of this application, and that the documents be made of record therein and appear among the "References Cited" on any patent to issue therefrom.

This Information Disclosure Statement is being filed within three months of the U.S. filing date OR before the mailing date of a first Office Action on the merits. No certification or fee is required.

This submission does not constitute a representation that a search has been made or that no better art exists and does not constitute an admission or representation that any of the listed documents is material or constitutes prior art. If it should be determined that any of the listed documents does not constitute prior art under the United States law, Applicants reserve the right

**Serial No. 09/800,980**

to present to the Office the relevant facts and law regarding the appropriate status of such document.

No certification or fee is believed to be required. However, the Commissioner is hereby authorized to charge any additional fees should any be required for this submission, or credit any overpayment to deposit account no. 08-0219.

Respectfully submitted,

HALE AND DORR LLP

A handwritten signature in cursive script, appearing to read "Scott M. Alter".

Scott M. Alter

Registration No. 32,879

1455 Pennsylvania Avenue, NW  
Washington, DC 20004

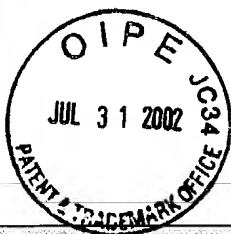
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Date: 7/31/02

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	5,220,517	06/15/93	Sierk et al.			08/31/90
	5,329,463	07/12/94	Sierk et al.			01/13/93
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						Yes	No
	2,050,247	08/29/91	Canada			X	
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	05-216896	08/27/93	Japan				X
	05-266029	10/15/93	Japan				X
	06-110894	04/22/94	Japan				X
	06-176994	06/24/94	Japan				X
	06-252236	09/09/94	Japan				X
	06-260380	09/16/94	Japan				X
	1072967A3	11/21/01	Europe			X	

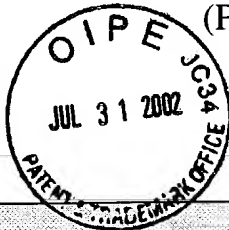
**OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)**

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	Zhou, Zhen-Hong and Rafael Reif. August 1995. "Epi-Film Thickness Measurements Using Emission Fourier Transform Infrared Spectroscopy—Part II: Real-Time <i>in Situ</i> Process Monitoring and Control." IEEE Transactions on Semiconductor Manufacturing, Vol. 8, No. 3.
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				APPLICANT Parris C.M. Hawkins et al.			
				FILING DATE March 8, 2001		GROUP 2121	
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